

REMARKS

The rejections of Claims 1-4, 9, 10, 12-18 and 20-22 as being anticipated by the Kawakami et al., publication, of Claims 1-4, 9, 10, 11[?], 12, 13, 15-18 and 20-22 as being anticipated by Jeun et al., and of Claims 1-4, 9, 10, and 12-22 as being anticipated by the Kurihara et al., publication, all under 35 U.S.C. § 102(e), are traversed. Likewise, the rejections of Claims 5-8 as being unpatentable over each of Kawakami et al., Jeun et al., and Kurihara et al., under 35 U.S.C. § 103(a) are also traversed. Reconsideration of each of these rejections is respectfully requested in light of the foregoing amendments and following comments.

Applicants attach hereto a certified translation of their Japanese priority document filed so as to establish an effective filing date of February 18, 2003, which antedates the Kawakami et al., publication date. Therefore, the latter publication does not qualify as prior art.

Figs. 1-7 of Jeun et al., clearly show that the electronic circuit elements 220 and the lead frame 210 are mounted on the common surface of the substrate. A part of the lead frame of 210 is prevented by the resin from protruding from the resin in a direction parallel to the thickness direction of the substrate and parallel to a transverse direction in which direction the substrate 260 extends to project outward with respect to an end of the lead frame 210 covered by the resin

in a cross section parallel to the thickness direction of the substrate and parallel to the protruding direction.

The Jeun et al., patent does not teach or suggest an arrangement as with the claimed invention herein where the lead frame faces the reverse surface in the thickness direction of the substrate to the substrate surface on which the circuit elements are mounted. Nor does this patent suggest an arrangement in which a part of the lead frame is prevented by the resin from protruding from the resin in a protruding direction parallel to the thickness direction of the substrate and perpendicular to a transverse direction in which direction the substrate extends so as to project outward with respect to an end of the lead frame covered by the resin in a cross section parallel to the thickness direction of the substrate and perpendicular to the protruding direction.

With regard to the Kurihara et al., publication, the Office Action misstates what the document actually discloses. Figs. 27A and 27B of Kurihara et al., show the substrate 5, 10 on which the electronic circuits are mounted does not extend so as to project outward with respect to an end of the lead frame 2 covered by the resin in a cross section parallel to the thickness direction of the substrate.

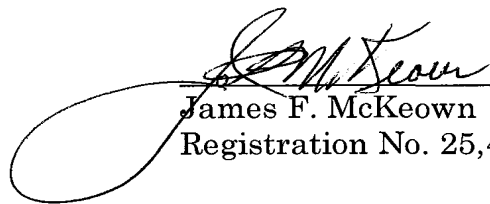
Accordingly, early and favorable consideration is earnestly solicited.

If there are any questions regarding this amendment or the application in general, a telephone call to the undersigned would be appreciated since this should expedite the prosecution of the application for all concerned.

If necessary to effect a timely response, this paper should be considered as a petition for an Extension of Time sufficient to effect a timely response, and please charge any deficiency in fees or credit any overpayments to Deposit Account No. 05-1323 (Docket #056203.52639US).

Respectfully submitted,

November 20, 2006



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